

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HARRY-HAK-LAY CHUANG	05/27/2014
WEI CHENG WU	05/27/2014
YA-CHEN KAO	05/27/2014
FANG-LAN CHU	05/27/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
<b>Street Address:</b>	NO. 8, LI-HSIN RD. 6
<b>Internal Address:</b>	HSIN-CHU SCIENCE PARK
<b>City:</b>	HSIN-CHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-77
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14296496
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(216)502-0601
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	216-502-0600
<b>Email:</b>	docketing@eschweilerlaw.com
<b>Correspondent Name:</b>	ESCHWEILER & ASSOCIATES, LLC.
<b>Address Line 1:</b>	629 EUCLID AVENUE, SUITE 1000
<b>Address Line 2:</b>	NATIONAL CITY BANK BUILDING
<b>Address Line 4:</b>	CLEVELAND, OHIO 44114
<b>ATTORNEY DOCKET NUMBER:</b>	TSMCP443USA
<b>NAME OF SUBMITTER:</b>	DAVID W. POTASHNIK
<b>SIGNATURE:</b>	/David W. Potashnik/
<b>DATE SIGNED:</b>	06/05/2014
<b>Total Attachments: 6</b>	
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**PATENT ASSIGNMENT**

**PARTIES TO THE ASSIGNMENT**

Assignor(s):

Harry-Hak-Lay Chuang  
51 Paya Lebar Crescent  
Singapore 536191

Assignor(s):

Wei Cheng Wu  
10F., No.196, Sec. 1, Shengli 7th St.  
Zhubei City, Hsinchu County  
302, Taiwan (R.O.C.)

Assignor(s):

Ya-Chen Kao  
No.73-1, Xikoutai, Fuxing Township  
Taoyuan County  
336, Taiwan (R.O.C.)

Assignor(s):

Fang-Lan Chu  
No.545, Sec. 1, Fengshi Rd.  
Fengyuan Dist., Taichung City  
420, Taiwan (R.O.C.)

Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.  
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park  
Hsin-Chu, Taiwan 300-77  
Republic of China

**AGREEMENT**

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled  
**"DUAL SILICIDE FORMATION METHOD TO EMBED FLASH MEMORY IN  
HKMG TECHNOLOGY "** for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration); or

☐ was filed on \_\_\_\_\_ and accorded U.S. Serial No. \_\_\_\_\_; or

☐ I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. \_\_\_\_\_,

filed on \_\_\_\_\_.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S)

hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

✓ 5/27/2014  
Date

✓   
Name 1<sup>st</sup> Inventor Harry-Hak-Lay Chuang

✓ 5/27/2014  
Date

✓ Wei Cheng Wu  
Name 2<sup>nd</sup> Inventor Wei Cheng Wu

✓ 5/27/2014  
Date

✓ Ya Chen Kao  
Name 3<sup>rd</sup> Inventor Ya-Chen Kao

✓ 5/27/2014  
Date

✓ Fang-Lan Chu  
Name 4<sup>th</sup> Inventor Fang-Lan Chu